



# Contactless Leadframe

## Metal stamped design optimized for contactless card applications

Linxens Contactless Leadframe (LOA2 / LOA4) is compatible with the standard mass market (OA2/OA4) industry design. Compliant with ISO standards, the Leadframe is optimized for assembly with a chip and particularly designed for contactless cards in the Financial services, Government, Transport and Access Control markets.

- Stamped copper with silver plating is available in two different copper metal thicknesses. One of which is LOA4 producing the thinnest module size of 200µm. Linxens' unique selective plating solution enables reduction of silver plating area thus overall costs can be optimized.
- Delivered in standard 35mm reel allowing module manufacturers to reuse their existing molding equipment for chip assembly. For card manufacturers, it enables full compatibility with the inlay production equipment.

Part Number	Designation	Die Pad Size class	Thickness class	Plating*
9X90001AA	Leadframe LOA2	3.4mm x 3.7mm	80µm	two-sided strip plating
9X90001BA	Leadframe LOA4	3.4mm x 3.7mm	60µm	two-sided strip plating

\*Contact Linxens to request for plating options and their specifications.

- Linxens' proprietary stamping and plating technology allow customized product design of Leadframes that can be used for other applications upon customer demands.
- Linxens offers chip module assembly on Contactless Leadframes. The Module Packaging Services datasheet will provide further information.

Feel free to contact Linxens for any requests of tailor-made solutions to meet specific requirements.



### SPECIALTY



#### Module Configurations

##### Material

- Material n° DIN EN CW452K
- Alloy CuSn6
- Hardness HV 180-230
- Thickness 0.06mm / 0.08mm
- Tolerance: ± 0.005 mm

##### Specifications

- Reel-to-reel format
- 35mm film
- Pitch 9.5 mm

##### Plating

- Min 1µm Ni all over
- Min 1.5µm Ag in selective plating area

##### Thickness

- Overall plating included:
- LOA2 0.082 +0.007 / -0.005mm
  - LOA4 0.062 +0.007 / -0.005mm

#### International Standards

- ISO/IEC 7810
- ISO/IEC 7816-1
- ISO/IEC 10373-1 and 10373-3
- MIL Std 883

#### Application Area

- Contactless chip card
- Government
- Transport
- Access control
- Financial services